



July 9, 2008

PCN Number: 0812

PCN Change Level: Major

Subject: Change in Mold Compound for BG and FG packages

Dear Customer,

The current mold compound (Nitto HC-100XJAA) that is used in Actel's BG and FG packages is being discontinued. Mold compound Nitto GE100L will replace Nitto HC-100XJAA. Table 1 lists affected devices.

Table 1. Affected Devices

Family	Device	Package	Speed	Temperature
SX	A54SX32	BG329, BG313	Std., -F, -1, -2	C, I, M
SX-A	A54SX16A	FG256	Std., -F, -1, -2	C, I, A, M
	A54SX32A	FG256, FG484, BG329	Std., -F, -1, -2	C, I, A, M
	A54SX72A	FG256, FG484	Std., -F, -1, -2	C, I, A, M
ProASIC®*	A500K130	BG456	Std.	C, I
	A500K180	BG456	Std.	C, I
	A500K270	BG456, FG676	Std.	C, I
ProASIC ^{PLUS} ®	APA150	BG456	Std.	C, I
	APA300	BG456	Std.	C, I, M
	APA450	FG484, BG456	Std.	C, I, A
	APA600	FG484, BG456, FG676	Std.	C, I, A, M
	APA750	BG456, FG676, FG896	Std.	C, I, A
	APA1000	BG456, FG896, FG1152	Std.	C, I, A, M
Axcelerator®	AX250	FG484	Std., -F, -1, -2	C, I, M
	AX500	FG484, FG676	Std., -F, -1, -2	C, I, M
	AX1000	FG484, FG676, FG896	Std., -F, -1, -2	C, I, M
	AX2000	FG896, FG1152	Std., -F, -1, -2	C, I, M

Note: * The ProASIC family has been discontinued.



Shipments with the Nitto GE100L mold compound will begin in October 2008.

If you have any questions, please contact Actel's Application Technical Support at tech@actel.com.

Regards,
Actel Corporation